

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on page 5, line 23 with the following amended paragraph:

Fig. 6 is a cross-section view of the contact pad of the circuit of Fig. 4 after welding of a metal wire. The tip of the metal wire forms a metal ball 50, conventionally made of gold, which rests on contact pad 31. Contact pad 31 has been hollowed during the welding almost down to substrate 32 and small aluminum projections have formed between ball 50 and passivation layer 33. The aluminum volume displaced in the welding process being relatively small, since the aluminum thickness is small, the pressure exerted on passivation layer 33 is small and causes no cracking. Further, the aluminum projections 51, 52 obtained on either side of ball 50 have small sizes and do not rise above passivation layer 33.

Please replace the paragraph beginning on page 6, line 14 with the following amended paragraph:

At the next step, illustrated in FIG. 7C, the entire structure is covered with a passivation layer 120.

Please replace the paragraph beginning on page 6, line 17 with the following amended paragraph:

At the next step, illustrated in FIG. 7E, metal portion 111 is etched to decrease its thickness. In this example, the etching is anisotropic and only the portion of metal portion 111 uncovered by passivation layer 120 is partially etched. In this example, the thickness of the exposed portion of portion 111 is decreased by half. It will be within the abilities of those skilled in the art to define the optimal etch process enabling maintaining an "ideal" metal thickness providing a good-quality welding.

Please replace the paragraph beginning on page 6, line 30 with the following amended paragraph:

At the next step, illustrated in FIG. 8C, coil 160 is covered with a protection layer 170. Generally, all the integrated circuit elements of which the thickness of the metal layer is desired to be kept are covered. Metal portion 161 intended to form a contact pad is then etched. The etch time is determined to obtain the desired thickness for the contact pads. In this example, the contact pad thickness is decreased by half.